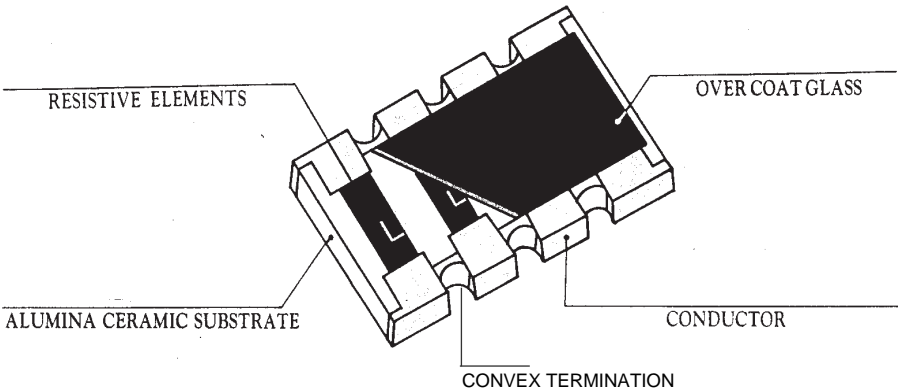


Thick Film Chip Resistor Arrays

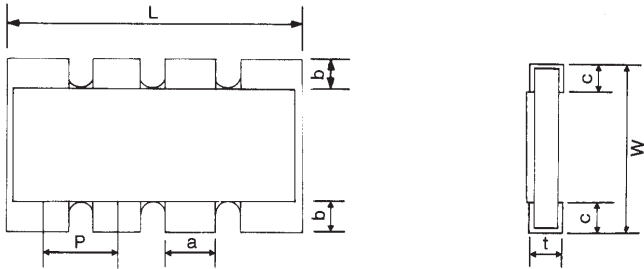
CONSTRUCTION

FEATURES

- High Density
- Automatic Placement
- Convex



DIMENSIONS IN MM



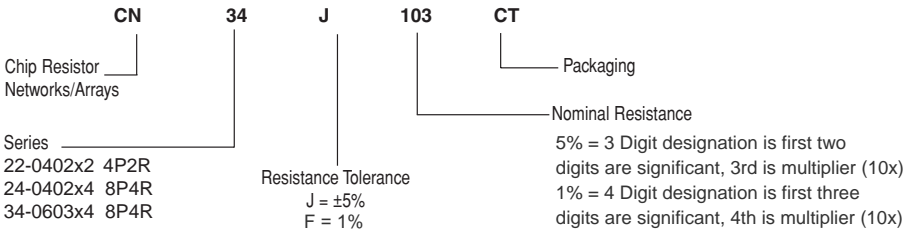
Unit: mm

| TYPE | L | W | t | P | a | b | c |
|------|---------|----------|----------|-----------|----------|----------|----------|
| CN34 | 3.2±0.1 | 1.6±0.15 | 0.55±0.1 | 0.8±0.5 | 0.45±0.1 | 0.3±0.2 | 0.3±0.2 |
| CN24 | 2.0±0.1 | 1.0±0.1 | 0.4±0.1 | 0.5±0.05 | 0.3±0.1 | 0.15±0.1 | 0.25±0.2 |
| CN22 | 1.0±0.1 | 1.0±0.1 | 0.35±0.1 | 0.65±0.05 | 0.3±0.1 | 0.15±0.1 | 0.25±0.2 |

RATING

| TYPE | Power Rating at 70°C | Max Working Voltage | Max Overload Voltage | Operating Temp. (°C) | Resistance Tolerance | Resistance Range (Ω) | Temp Coefficient ppm/°C |
|--------------|----------------------|---------------------|----------------------|----------------------|----------------------|----------------------|-------------------------|
| CN34 | 1/16W | 50V | 100V | -55~+125°C | F±1% J±5% | 0Ω~1MΩ | ±200ppm/°C |
| CN24 CN22 | 1/16W | 50V | 100V | -55~+125°C | F±1% J±5% | 0Ω~1MΩ | ±250ppm/°C |

Ordering Information



Note: Calchip has completed the Lead-Free transition. All parts shipped will be Lead-Free. The customer designator of "LF" is no longer available. Lead-Free material will continue to have an LF at the end of the Lot Code and a green RoHS symbol on the label.

Thick Film Chip Resistor Arrays

1.0 Number of Element

Depend on its element's number. (2-2 element. 4-4 element)

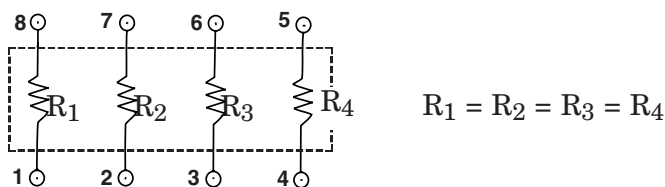
2.0 Resistance Tolerance

F: $\pm 1\%$ J: $\pm 5\%$

3.0 Nominal Resistance

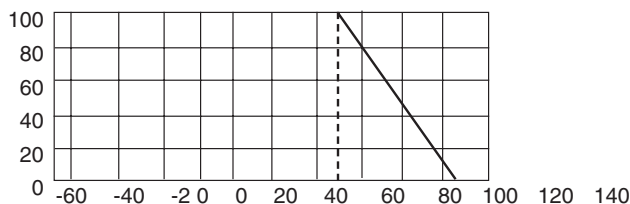
Example: 103, 10 is effective digit, 3 is a multiple which represents the cube of 10, zero number is three.

4.0 Schematics



5.0 Power Derating Curve

The resistors operated in ambient temperatures above 70°C, power rating must be derated in accordance with the curve in Figure 1.



5.1 Rated Voltage

The value of rated voltage shall be determined from formula (1).

$$E = \sqrt{P \times R} \dots (1)$$

E = Rated Voltage (V)

P = Power Rating (W)

R = Nominal Resistance (Ω)

6.0 Electrical / Machine Characteristics and Test Methods

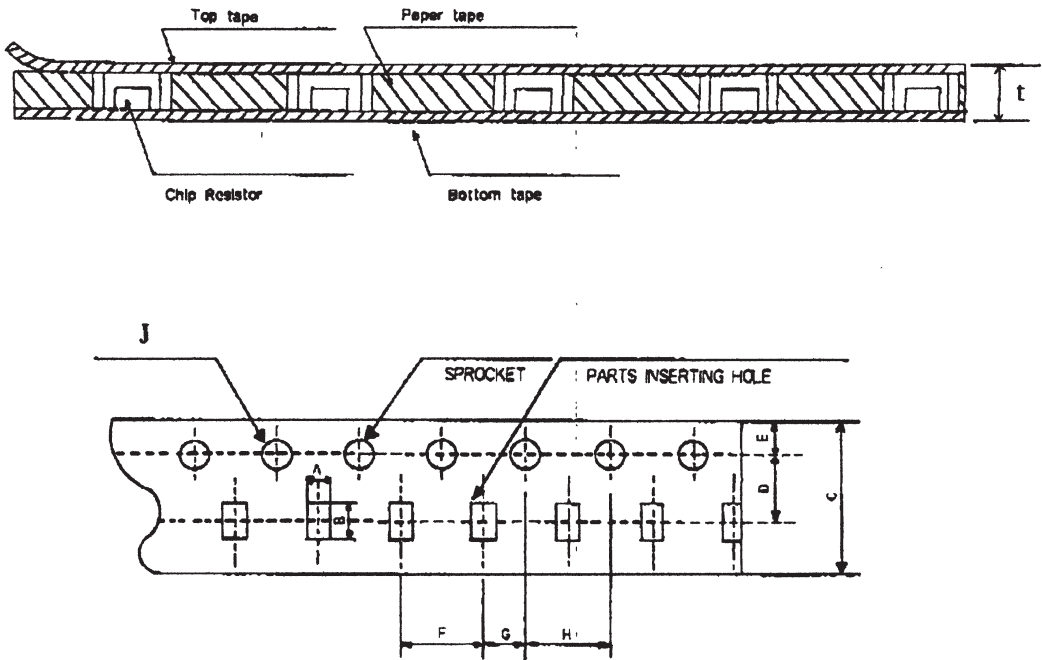
| Item | Specifications | Test Methods |
|---------------------------------|--|---|
| Temperature Coefficient | TCR: ± 200 ppm | Inspection Temp. Cold: $+25^{\circ}\text{C} \sim -55^{\circ}\text{C}$ Hot: $+25^{\circ}\text{C} \sim +125^{\circ}\text{C}$ |
| Short Time Overload | $\pm(2\%+0.05\Omega)$ | 1. Apply 2.5 x rated voltage for 5 sec. 2. Wait 30 minutes 3. Measure resistance value |
| Load Life | $\pm(3\%+0.05\Omega)$ | 1. Dwell in chamber at $70 \pm 2^{\circ}\text{C}$ for ON: 90 min. at rated voltage; then OFF: 30 min. 2. Perform 1,000 hours cyclically |
| Load Life in Humidity | $\pm(3\%+0.05\Omega)$ | 1. Dwell in humidity chamber at $40 \pm 2^{\circ}\text{C}$ and 95% RH for ON: 90 min. at rated voltage; then OFF: 30 min. 2. Perform 1,000 hours cyclically |
| Temperature Cycling | $\pm(1\%+0.05\Omega)$ | 1. $-55 \pm 3^{\circ}\text{C} \sim 125 \pm 3^{\circ}\text{C}$, make 5 cycles. 2. Released 1 hour in room temp., then measure value. |
| Effect of Soldering | $\pm(2.5\%+0.05\Omega)$ Non-damage by machinery | 1. Immersed in molten solder at $270 \pm 5^{\circ}\text{C}$ for 10 ± 0.1 sec. 2. Released 1 hour in room temp., then measure value. |
| Solderability | 95% coverage min. | 1. Immersed in rosin solution for 5~10 seconds. 2. Re-immersed in solder pot at $230 \pm 5^{\circ}\text{C}$ for 3 ± 0.5 sec |
| Intermittent Overload | $\pm(5\%+0.1\Omega)$ | 1. Perform 10,000 voltage cycles as follows: ON (2.5 x rated voltage or current) 1 sec. and OFF 25 sec. 2. Released 30 min. without loading. 3. Measure resistance. |
| Dielectric Withstanding Voltage | No evidence of mechanical damage | Apply 300VAC for 1 second |
| Insulation Resistance | $10^8 \Omega$ min | Apply 100VDC. |

Thick Film Chip Resistor Arrays

Taping Specification

Carrier Tape

Unit in mm

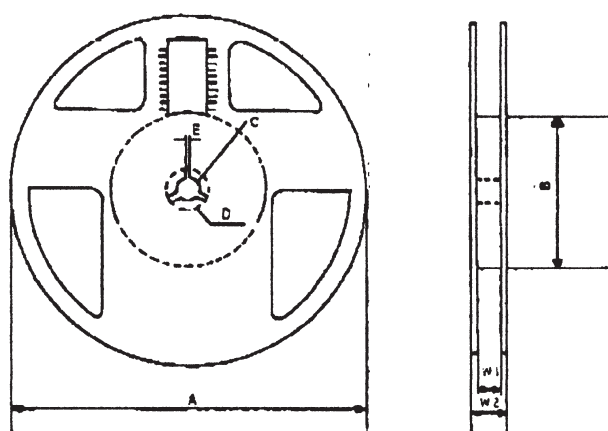
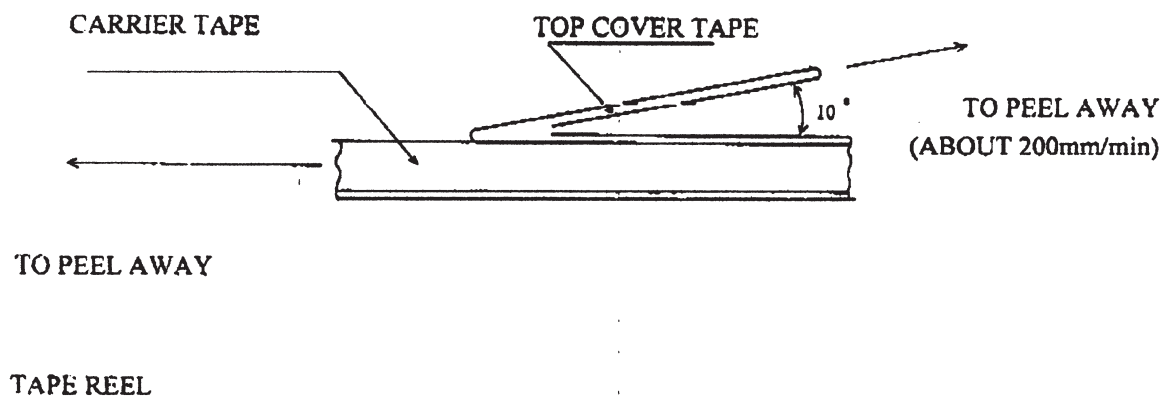


Paper Tape

| Type | | A | B | C | D | E | F | G | H | J | t |
|------|--------|----------|---------|---------|----------|----------|---------|----------|---------|------------|---------|
| CN34 | 5,000 | 2.0±0.2 | 3.6±0.2 | 8.0±0.1 | 3.5±0.05 | 1.75±0.1 | 4.0±0.1 | 2.0±0.05 | 4.0±0.1 | 1.5±0.1 | 1.0 |
| CN24 | 10,000 | 2.0±0.15 | 2.4±0.2 | 8.0±0.2 | 3.5±0.05 | 1.75±0.1 | 4.0±0.1 | 2.0±0.05 | 4.0±0.1 | 1.5±0.1/-0 | .84±.01 |

Thick Film Chip Resistor Arrays

The top fixed tape for each carrier shall have an adhesion peel strength of 10 to 50g, measure methods is shown below to peel away.



| Type | A | B | C | D | E | W1 | W2 |
|------|--------------------|-------------------|-------------------|-------------|---------------|----------------|----------------|
| CN34 | $\phi 178 \pm 2.0$ | $\phi 80 \pm 2.0$ | $\phi 13 \pm 0.5$ | $\phi 21.0$ | 2.0 ± 0.5 | 10.0 ± 1.0 | 12.5 ± 1.0 |
| CN24 | $\phi 178 \pm 2.0$ | $\phi 80 \pm 2.0$ | $\phi 13 \pm 0.5$ | $\phi 21.0$ | 2.0 ± 0.5 | 10.0 ± 1.0 | 12.5 ± 1.0 |
| CN22 | $\phi 178 \pm 2.0$ | $\phi 80 \pm 2.0$ | $\phi 13 \pm 0.5$ | $\phi 21.0$ | 2.0 ± 0.5 | 9.0 ± 1.0 | 11.4 ± 2.0 |